

1. Disassembly Procedures

**S1** Turn off the monitor.

**S2** To remove the stand

Place the monitor on a soft cloth or cushion at the edge of the desk.

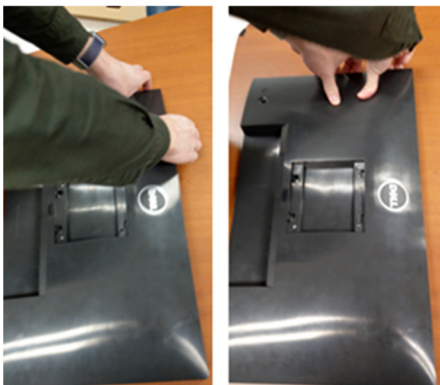
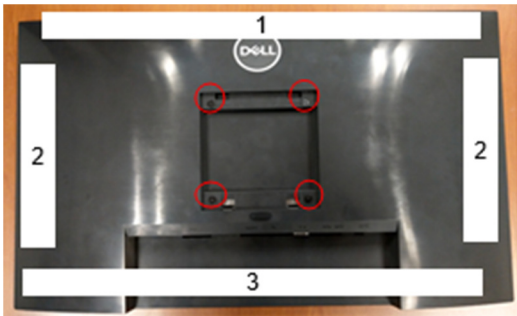
Press and hold the stand release button at the back of the display.

Lift the stand assembly up and away from the monitor.



**S3** Unlock 4 RC screws

Disassemble Rear Cover from Middle Frame according to the sequence shown in the picture



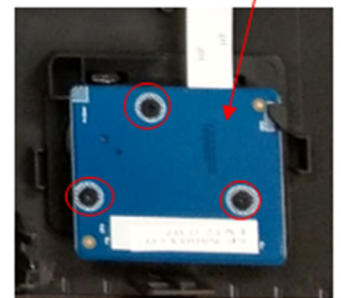
(Screw Torque: 9±1kgf)

**S4** Pull out CTRL FFC from I/F BD to take off Rear Cover



**S5** Tear off 1 tape from CTRL BD FFC on Rear Cover

Unlock 3 screws to disassemble CTRL BD from Rear Cover

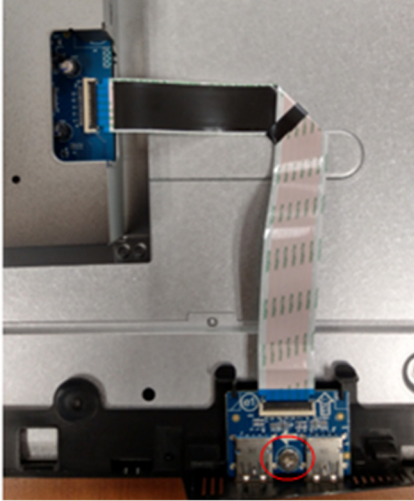


(Screw Torque: 1.4±0.1kgf)

**S6** Pull out USB FFC from USB BD and I/F BD

Unlock 1 screw on USB BD

Disassemble USB BD from Middle Frame



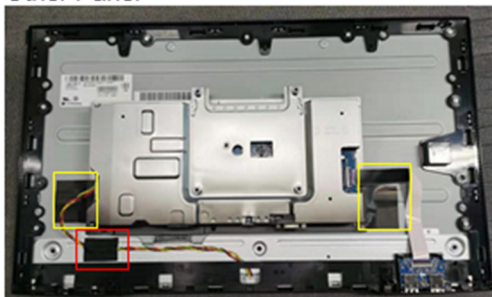
(Screw Torque:  $4.5 \pm 0.5$ kgf)

**S7** Tear off adhesive tape on Backlight Wire

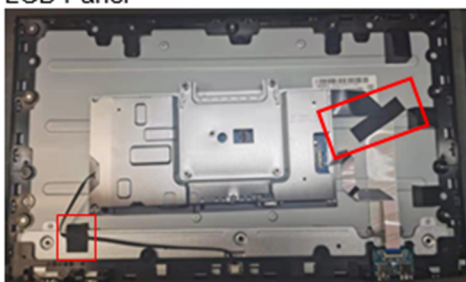
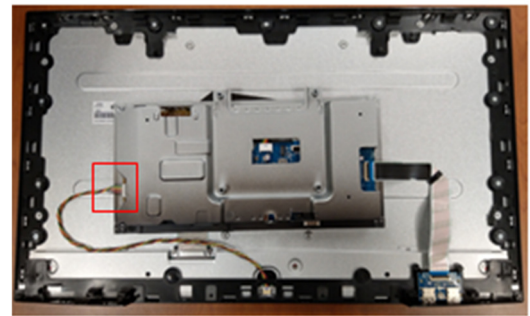
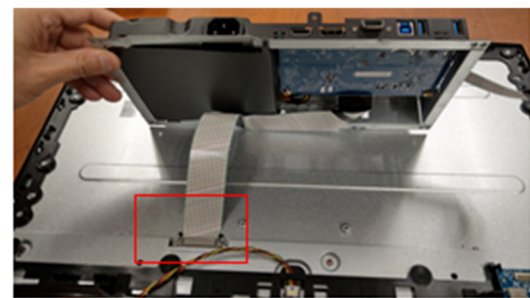
Tear off adhesive tape on LVDS Cable  
(Note: Only for LG panel)

Tear off two tapes to disassemble Main SHD from panel

Other Panel



LGD Panel

**S8** Pull out Backlight Wire from SPS BD**S9** Pull out LVDS cable and take off Main SHD from panel**S10** Unlock 9 screws on Middle Frame

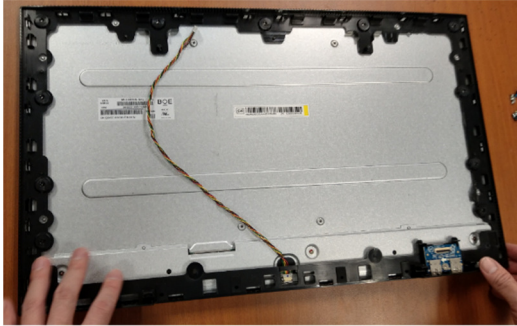
Unlock 2 screws on Bezel Chin



(Screw Torque-MF:  $3.5 \sim 4.0$ kgf)

(Screw Torque-BZL Chin:  $2.0 \pm 0.1$ kgf)

**S11** Disassemble Middle Frame and Bezel Chin from Panel

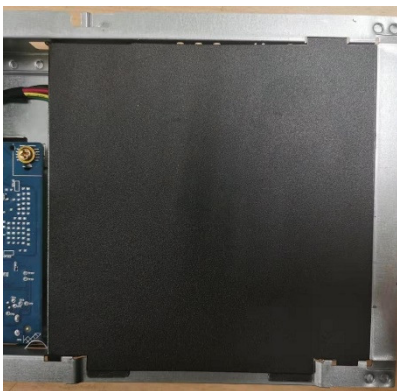


Bezel Chin

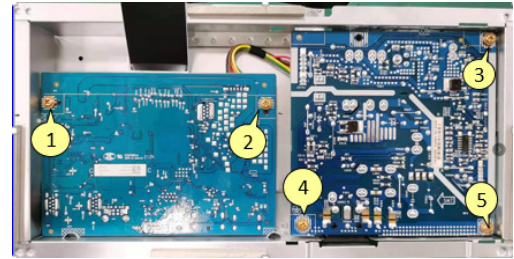
**S12** Pull out Backlight Wire from panel



**S13** Disassemble Mylar from Main SHD



**S14** Unlock 5 PCB screws and 2 hex screws



(Screw Torque-PCB:  $8.5 \pm 1 \text{kgf}$ )  
(Screw Torque-Hex:  $5 \pm 0.6 \text{kgf}$ )

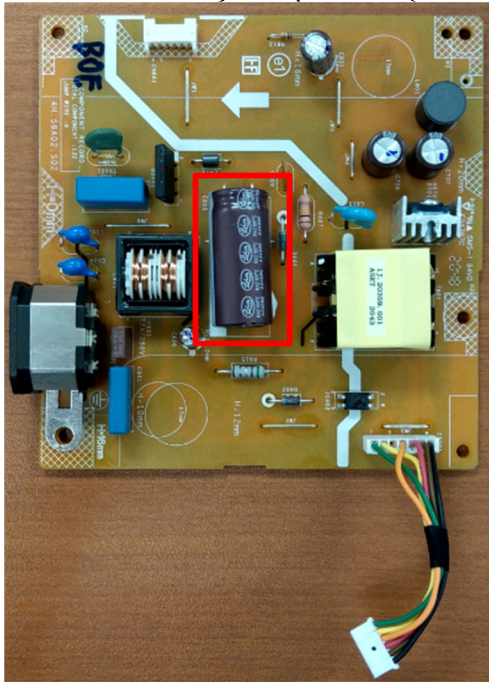
**S15** Take out I/F BD and SPS BD from Main SHD



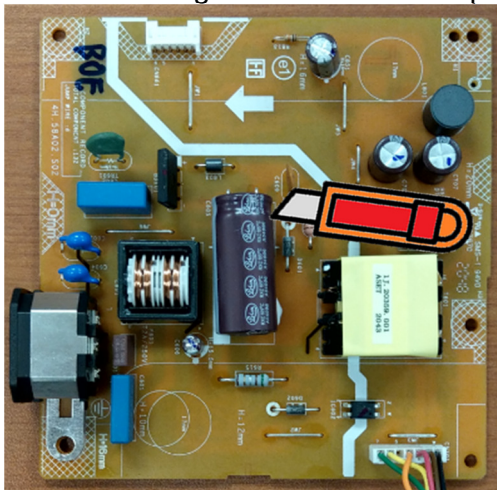
**S16** Pull out LVDS cable and SPS BD cable from I/F BD



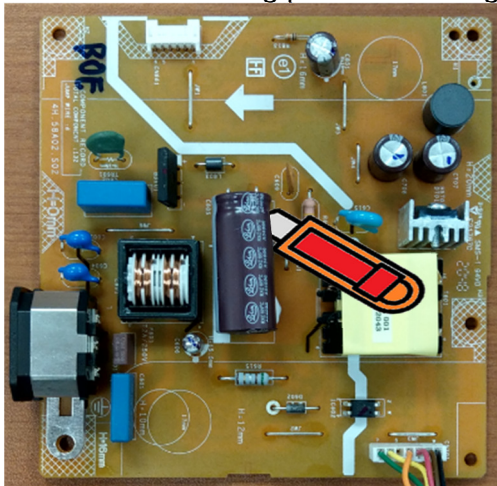
**S17** Remove electrolyte capacitors (red mark) from printed circuit boards



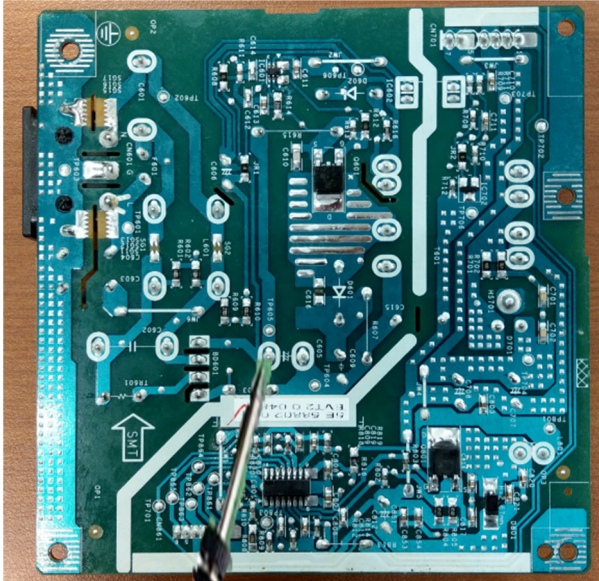
S17-1 Cut the glue between bulk cap. and PCB with a knife



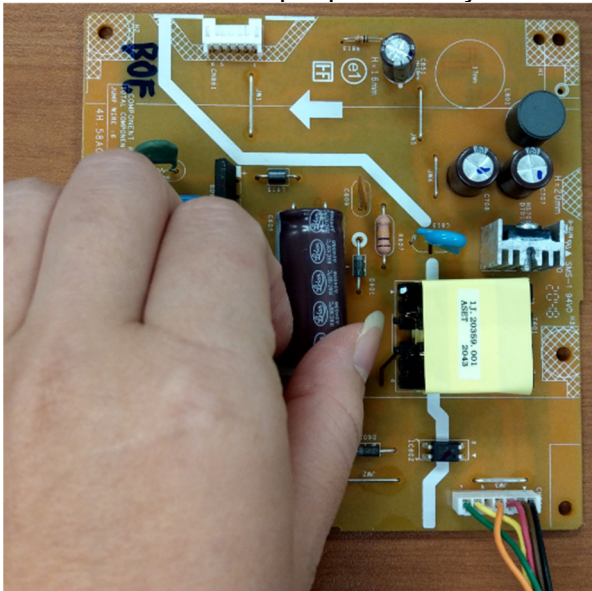
S17-2 Ensure cutting path within the glue, don't touch bulk cap. or PCB



S17-3 Take out bulk cap. pin solder with soldering iron and absorber



S17-4 Lift the bulk cap. up and away from the PCB



## 2. Product material information

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Capacitors / condensers (containing PCB/PCT)	No used
Mercury containing components	No used
Batteries	No used
Printed circuit boards (with a surface greater than 10 square cm)	Product has printed circuit boards (with a surface greater than 10 square cm)
Component contain toner, ink and liquids	No used
Plastic containing BFR	No used
Component and waste contain asbestos	No used
CRT	No used
Component contain CFC, HCFC, HFC and HC	No used
Gas discharge lamps	No used
LCD display > 100 cm <sup>2</sup>	Product has an LCD greater than 100 cm <sup>2</sup>
External electric cable	Product has external cables
Component contain refractory ceramic fibers	No used
Component contain radio-active substances	No used
Electrolyte capacitors (height > 25mm, diameter > 25mm)	Product has electrolyte capacitors (height >25mm, diameter > 25mm)

## 3. Tools Required

List the type and size of the tools that would typically can be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description:

- Screwdriver
- Scraper Bar
- Penknife
- Soldering iron and absorber